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FDN5630

60V N-Channel PowerTrench® MOSFET

General Description

This N-Channel MOSFET has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers.

This MOSFET features very low $R_{\text{DS(ON)}}$ in a small SOT23 footprint. ON Semiconductor's PowerTrench technology provides faster switching than other MOSFETs with comparable $R_{\text{DS(ON)}}$ specifications.

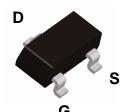
The result is higher overall efficiency with less board space.

Features

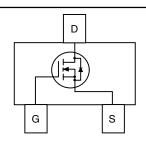
- 1.7 A, 60 V. $R_{DS(ON)} = 0.100 \Omega$ @ $V_{GS} = 10 V$ $R_{DS(ON)} = 0.120 \Omega$ @ $V_{GS} = 6 V$.
- Optimized for use in high frequency DC/DC converters.
- · Low gate charge.
- · Very fast switching.
- SuperSOT[™] 3 provides low R_{DS(ON)} in SOT23 footprint.

Applications

- DC/DC converter
- Motor drives



SuperSOT[™]-3



Absolute Maximum Ratings T_A = 25 C unless otherwise noted

Symbol	Parameter		Ratings	Units
V _{DSS}	Drain-Source Voltage		60	V
V _{GSS}	Gate-Source Voltage		±20	V
I _D	Drain Current - Continuous	(Note 1a)	1.7	А
	- Pulsed		10	
P _D	Power Dissipation for Single Operation	(Note 1a)	0.5	W
		(Note 1b)	0.46	
T _J , T _{stg}	Operating and Storage Junction Temperature Range		-55 to +150	°C

Thermal Characteristics

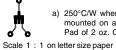
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1a)	250	°C/W
R _e JC	Thermal Resistance, Junction-to-Case	(Note 1)	75	°C/W

Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape Width	Quantity
5630	FDN5630	7	8mm	3000 units

BV _{DSS} \[\Delta \text{VDSS} \\ \Delta \text{TJ} \] IDSS IGSSF IGSSR	Drain-Source Breakdown Voltage Breakdown Voltage Temperature Coefficient Zero Gate Voltage Drain Current Gate-Body Leakage Current, Forward Gate-Body Leakage Current, Reverse Interestics (Note 2)	$\begin{split} V_{GS} &= 0 \text{ V, } I_D = 250 \mu\text{A} \\ I_D &= 250 \mu\text{A, Referenced to } 25^{\circ}\text{C} \\ V_{DS} &= 48 \text{ V, } V_{GS} = 0 \text{ V} \\ V_{GS} &= 20 \text{ V, } V_{DS} = 0 \text{ V} \\ \end{split}$	60	63	1 100	V mV/°C μA nA
ΔBV _{DSS} ΔT _J IDSS IGSSF IGSSR On Chara	Breakdown Voltage Temperature Coefficient Zero Gate Voltage Drain Current Gate-Body Leakage Current, Forward Gate-Body Leakage Current, Reverse Icteristics (Note 2)	$I_D = 250 \ \mu\text{A}, \text{Referenced to } 25^{\circ}\text{C}$ $V_{DS} = 48 \ \text{V}, \ V_{GS} = 0 \ \text{V}$ $V_{GS} = 20 \ \text{V}, \ V_{DS} = 0 \ \text{V}$	60	63	100	mV/°C μΑ
ΔT _J I _{DSS} I _{GSSF} I _{GSSR} On Chara	Coefficient Zero Gate Voltage Drain Current Gate-Body Leakage Current, Forward Gate-Body Leakage Current, Reverse Interestics (Note 2)	V _{DS} = 48 V, V _{GS} = 0 V V _{GS} = 20 V, V _{DS} = 0 V		63	100	μΑ
Igssr Igssr On Chara	Gate-Body Leakage Current, Forward Gate-Body Leakage Current, Reverse Interistics (Note 2)	V _{GS} = 20 V, V _{DS} = 0 V			100	
I _{GSSR}	Forward Gate-Body Leakage Current, Reverse acteristics (Note 2)	30 1 , 30 1				nA
On Chara	Reverse (Note 2)	V _{GS} = -20 V, V _{DS} = 0 V			400	1
					-100	nA
V _{GS(th)}	Cata Thuashald Valtage					
CO(iii)	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	1	2.4	3	V
$\Delta V_{GS(th)} \over \Delta T_J$	Gate Threshold Voltage Temperature Coefficient	I_D = 250 μ A,Referenced to 25°C		-6.9		mV/°C
R _{DS(ON)}	Static Drain-Source On-Resistance	$V_{GS} = 10 \text{ V}, I_D = 1.7 \text{ A}$ $V_{GS} = 10 \text{ V}, I_D = 1.7 \text{ A}, T_J = 125^{\circ}\text{C}$ $V_{GS} = 6 \text{ V}, I_D = 1.6 \text{ A}$		0.073 0.127 0.083	0.100 0.180 0.120	Ω
$I_{D(on)}$	On-State Drain Current	V _{GS} = 10 V, V _{DS} = 1.7 V	5			Α
g fs	Forward Transconductance	V _{DS} = 10 V, I _D = 1.7 A		6		S
Dvnamic	Characteristics					
C _{iss}	Input Capacitance	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V},$		400	560	pF
Coss	Output Capacitance	f = 1.0 MHz		65	95	pF
C _{rss}	Reverse Transfer Capacitance	1		27	40	pF
Switching	Characteristics (Note 2)	•				
$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 30 \text{ V}, I_D = 1 \text{ A},$ $V_{GS} = 10 \text{ V}, R_{GEN} = 6 \Omega$		10	20	ns
t _r	Turn-On Rise Time			6	15	ns
t _{d(off)}	Turn-Off Delay Time			15	28	ns
t _f	Turn-Off Fall Time			5	15	ns
Qg	Total Gate Charge	$V_{DS} = 20 \text{ V}, I_{D} = 1.7 \text{ A},$ $V_{GS} = 10 \text{ V},$		7	10	nC
Q _{gs}	Gate-Source Charge			1.6		nC
Q_{gd}	Gate-Drain Charge	1 1		1.2		nC
Drain-Sou	urce Diode Characteristics a	and Maximum Ratings				
l _S	Maximum Continuous Drain-Source				0.42	Α
V_{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_S = 0.42 \text{ A}$ (Note 2)		0.72	1.2	V

1: $R_{a,l,A}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{a,l,C}$ is guaranteed by design while $R_{a,l,A}$ is determined by the user's board design.



a) 250°C/W when mounted on a 0.02 in² Pad of 2 oz. Cu.



b) 270°C/W when mounted on a minimum pad.

2: Pulse Test: Pulse Width $\leq\!300~\mu\text{s},$ Duty Cycle $\leq\!2.0\%$

Typical Characteristics

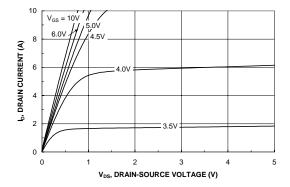


Figure 1. On-Region Characteristics.

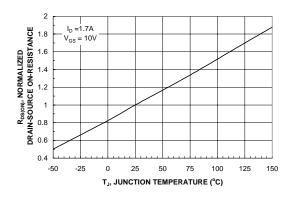


Figure 3. On-Resistance Variation with Temperature.

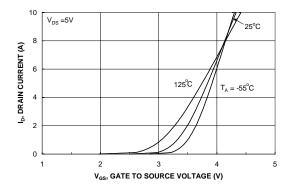


Figure 5. Transfer Characteristics.

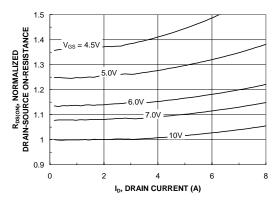


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

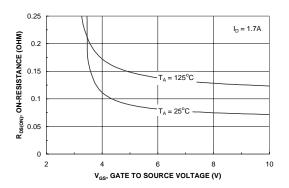


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

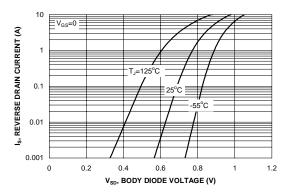
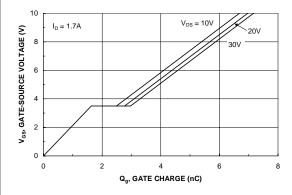


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics (continued)



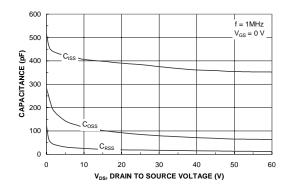
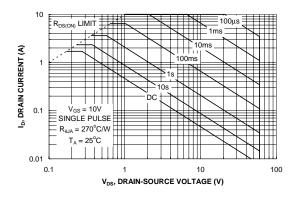


Figure 7. Gate Charge Characteristics.





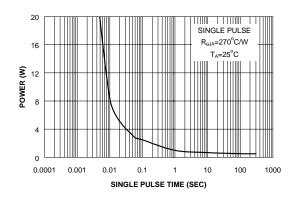


Figure 9. Maximum Safe Operating Area.

Figure 10. Single Pulse Maximum Power Dissipation.

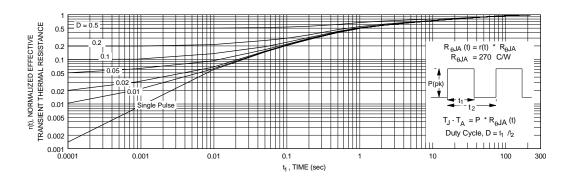


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1b. Transient themal response will change depending on the circuit board design.

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